



Video Products Technical Bulletin 30-2002-175R2

DATE: June 1, 2009

SUBJECT: POWER AND H OUT TRANSISTOR FAILURE



MODEL:

BVM-D9H1A
BVM-D9H1E
BVM-D9H1U
BVM-D9H5A
BVM-D9H5E
BVM-D9H5U

DESCRIPTION

The H OUT transistor may become damaged, resulting in power failure, under the following conditions:

- The BKM-142HD option board is installed.
- The signal cable is pulled out and plugged in, or the signal is cut off after a 720/60p HD-SDI signal is input.

To prevent damage to the transistor, perform the following modification procedure.



SERIAL NO:

BVM-D9H1A Up to 2,000,027
BVM-D9H1E Up to 2,000,060
 BVM-D9H1U Up to 2,000,410
BVM-D9H5A Up to 2,000,025
BVM-D9H5E Up to 2,000,190
 BVM-D9H5U Up to 2,000,689

Italicized information in green applies to customers outside the United States.

PARTS REQUIRED

Part No.	Description	Qty.
MBVMDOS/3	Software V1.17	1
8-719-911-19	Diode, 1SS119	1
1-136-165-00	Cap, 0.1 μ F/50V	1
1-247-903-00	Res, 1 M Ω	1
1-107-913-11	Cap, 470 μ F	1
8-759-239-34	IC, TC74HC4538AF	1

ORDERING INFORMATION

To order parts online, go to: <http://www.sony.com/servicesplus>.
 For service or parts ordering assistance, refer to the following document, which lists all contact telephone numbers:

Technical Bulletin 00-1999-000

**MODIFICATION PROCEDURE**

1. Upgrade software from V1.16 to V1.17.

CAUTION: If the harness that connects the T board (CN801) to the B board (CN301) is too close to the DY, noise may interfere with the H sync signal on the harness, causing the relay to malfunction (chatter). The harness may also pick up an H pulse signal, even though no video signal is input.

To prevent interference, reroute the harness that is folded in the purse lock on the T board side 180°, so that the harness exits the purse lock away from the DY and is 20–30 mm away from the DY.

DPMO02-034R3

P Board (Side B)

2. Replace C554 with a new 470 μF capacitor.

D Board (Side B)

3. Remove C2632 (220 μF), which is soldered in parallel with R2553 (zone B-6).

(See Figure 1.)

4. Modify the H SYNC circuit on the D board by adding individual components as follows:
 - a. Remove IC2505 (zone D-7).
 - b. Cut the trace leading from IC2505 pin 3.
 - c. Replace IC2505 with a new IC (TC74HC4538AF).
 - d. Solder the cathode of a new diode (1SS119) to IC2505 pin 3.
 - e. Solder the anode of the diode to the thru-hole on the lower left side of C2583.
 - f. Solder a 0.1 μF capacitor between pins 3 and 8 of IC2505.
 - g. Solder a 1 M Ω resistor to both leads of the capacitor.

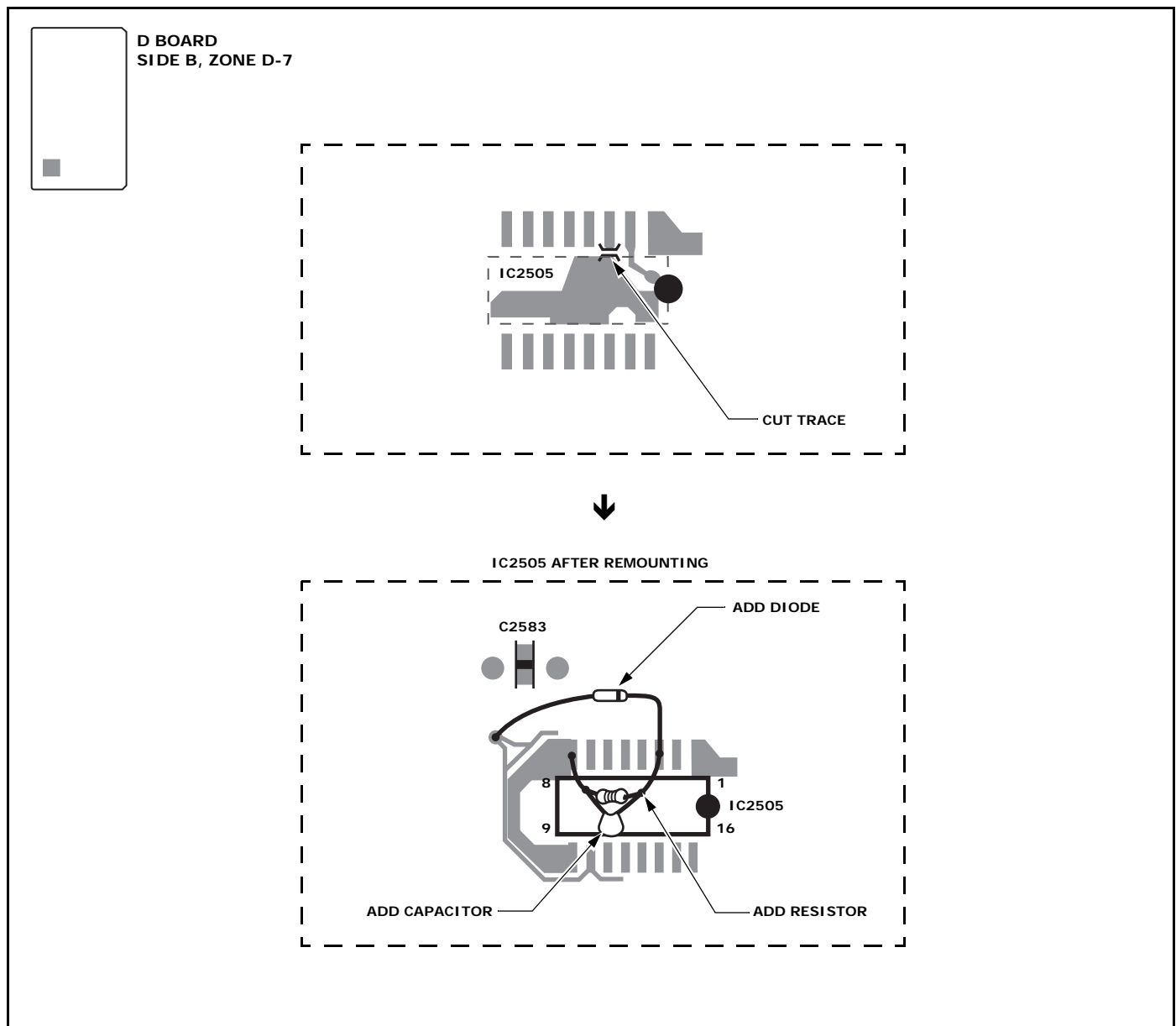


Figure 1